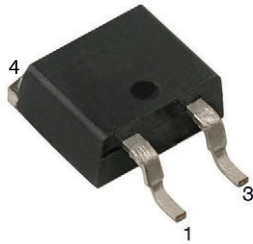
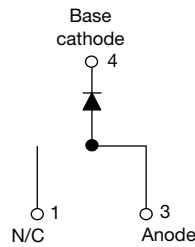


Hyperfast Rectifier, 15 A FRED Pt® G5


D²PAK 2L (TO-263AB 2L)


FEATURES

- Best in class forward voltage drop and switching losses trade off
- Optimized for high speed operation
- 175 °C maximum operating junction temperature
- Polyimide passivation
- Meets MSL level 1, per J-STD-020, LF maximum peak of 245 °C
- AEC-Q101 qualified meets JESD 201 class 2 whisker test
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912


RoHS
 COMPLIANT
 HALOGEN
FREE

LINKS TO ADDITIONAL RESOURCES



PRIMARY CHARACTERISTICS	
$I_{F(AV)}$	15 A
V_R	600 V
V_F at I_F at 125 °C	1.15 V
t_{rr} (typ.)	22 ns
T_J max.	175 °C
Package	D²PAK 2L (TO-263AB 2L)
Circuit configuration	Single

DESCRIPTION / APPLICATIONS

Featuring a unique combination of low conduction and switching losses, this rectifier is the right choice for soft switched and resonant converters, as well as medium frequency hard switching converters. This device is specifically designed to improve efficiency of high speed LLC output rectification stages of EV / HEV battery charging stations and high frequency stages of UPS applications.

MECHANICAL DATA

Case: D²PAK 2L (TO-263AB 2L)

Molding compound meets UL 94 V-0 flammability rating

Terminals: matte tin plated leads, solderable per J-STD-002

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Repetitive peak reverse voltage	V_{RRM}		600	V
Average rectified forward current	$I_{F(AV)}$	$T_C = 136\text{ °C}$, $D = 0.50$	15	A
Repetitive peak forward current	I_{FRM}	$T_C = 136\text{ °C}$, $D = 0.50$, $f = 20\text{ kHz}$	30	
Non-repetitive peak surge current	I_{FSM}	$T_C = 25\text{ °C}$, $t_p = 10\text{ ms}$, sine wave	200	
Operating junction and storage temperature	T_J , T_{Stg}		-55 to +175	°C

ELECTRICAL SPECIFICATIONS ($T_J = 25\text{ °C}$ unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	V_{BR} , V_R	$I_R = 100\text{ }\mu\text{A}$	600	-	-	V
Forward voltage	V_F	$I_F = 15\text{ A}$	-	1.3	1.6	
		$I_F = 15\text{ A}$, $T_J = 125\text{ °C}$	-	1.15	-	
Reverse leakage current	I_R	$V_R = V_R$ rated	-	-	10	μA
		$T_J = 125\text{ °C}$, $V_R = V_R$ rated	-	-	500	
Junction capacitance	C_T	$V_R = 200\text{ V}$	-	25	-	pF
Series inductance	L_S	Measured to lead 5 mm from package body	-	8	-	nH



DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Reverse recovery time	t _{rr}	I _F = 1.0 A, di _F /dt = 100 A/μs, V _R = 30 V	-	22	-	ns
		T _J = 25 °C	-	31	-	
		T _J = 125 °C	-	43	-	
Peak recovery current	I _{RRM}	T _J = 25 °C	-	15	-	A
		T _J = 125 °C	-	22	-	
Reverse recovery charge	Q _{rr}	T _J = 25 °C	-	255	-	nC
		T _J = 125 °C	-	622	-	
Reverse recovery time	t _{rr}	T _J = 25 °C	-	38	-	ns
		T _J = 125 °C	-	49	-	
Peak recovery current	I _{RRM}	T _J = 25 °C	-	16	-	A
		T _J = 125 °C	-	24	-	
Reverse recovery charge	Q _{rr}	T _J = 25 °C	-	316	-	nC
		T _J = 125 °C	-	782	-	

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Thermal resistance, junction-to-case	R _{thJC}		-	-	1.72	°C/W
Weight			-	2.0	-	g
			-	0.07	-	oz.
Maximum junction and storage temperature range	T _J , T _{Stg}		-55	-	175	°C
Marking device		Case style 2L D ² PAK (2L TO-263AB)	E5TH1506SH			

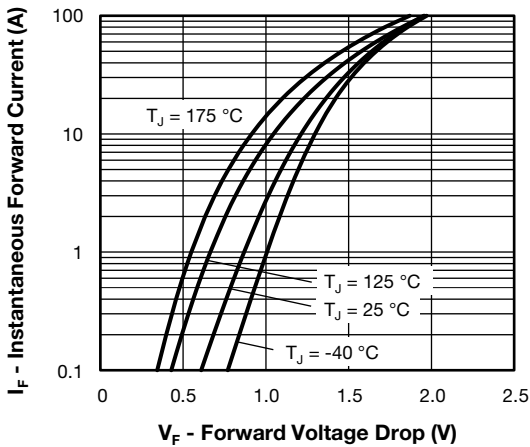


Fig. 1 - Forward Voltage Drop Characteristics, Per Leg

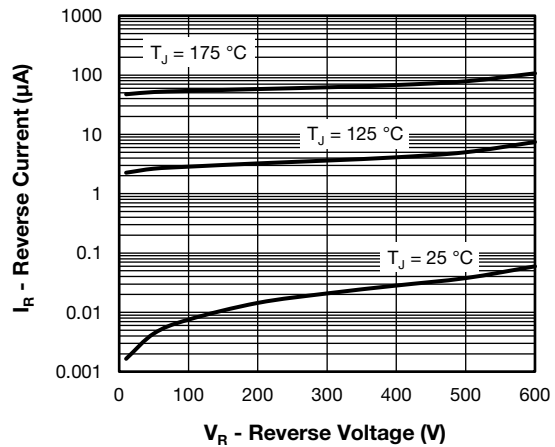


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage, Per Leg

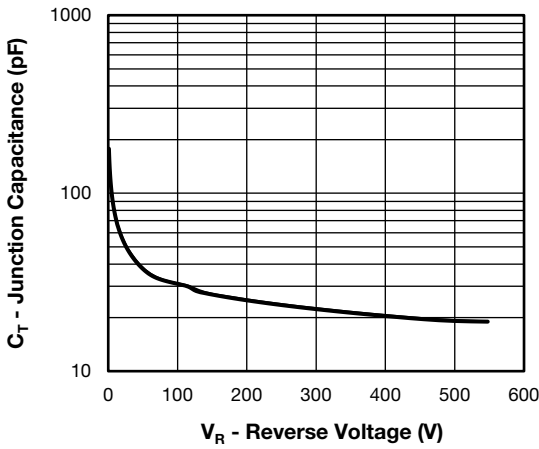


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage, Per Leg

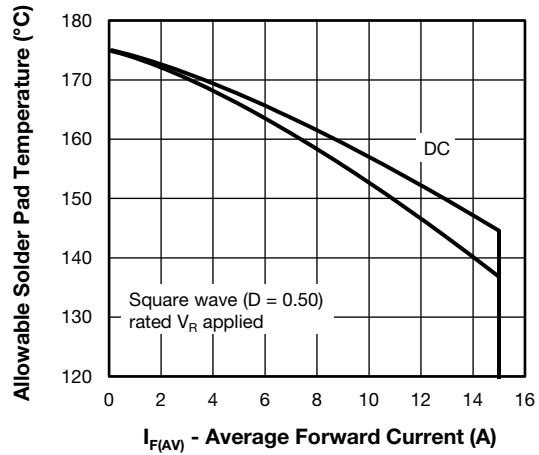


Fig. 4 - Maximum Allowable Case Temperature vs. Average Forward Current, Per Leg

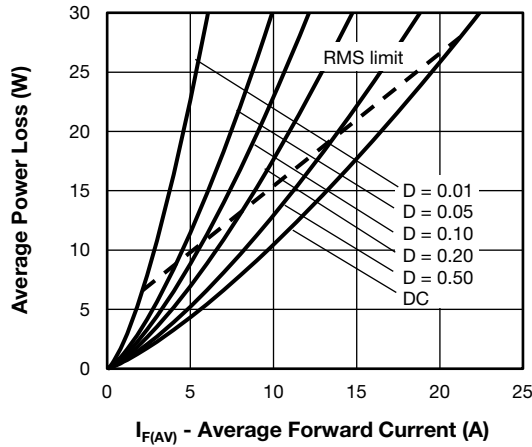


Fig. 5 - Forward Power Loss Characteristics, Per Leg

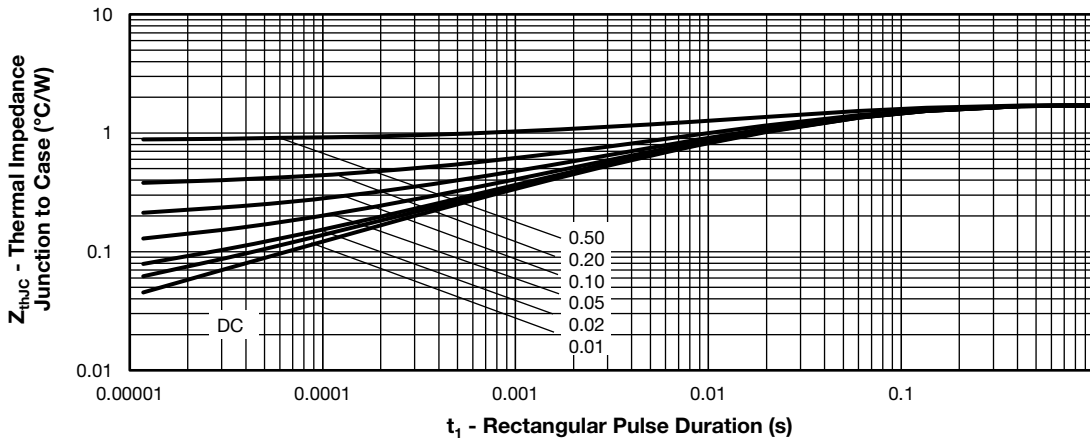


Fig. 6 - Transient Thermal Impedance, Junction to Case, Per Leg

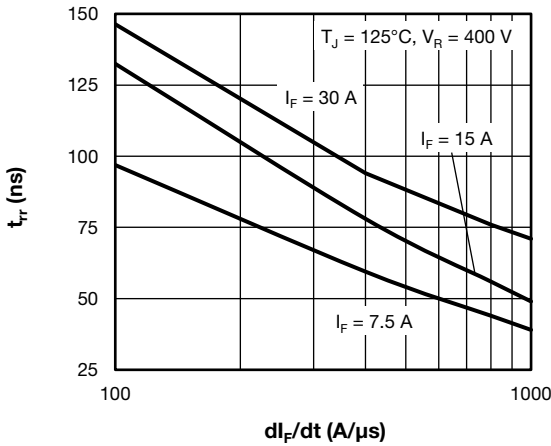


Fig. 7 - Typical Reverse Recovery Time vs. di_F/dt , Per Leg

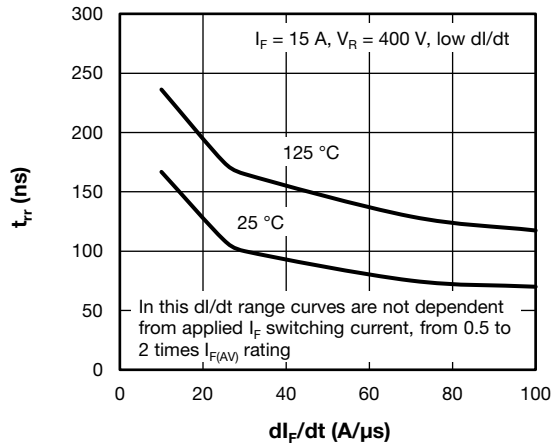


Fig. 10 - Typical Reverse Recovery Time vs. di_F/dt , Per Leg

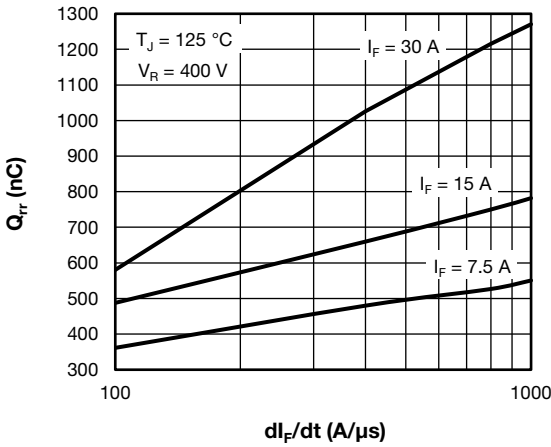


Fig. 8 - Typical Reverse Recovery Charge vs. di_F/dt , Per Leg

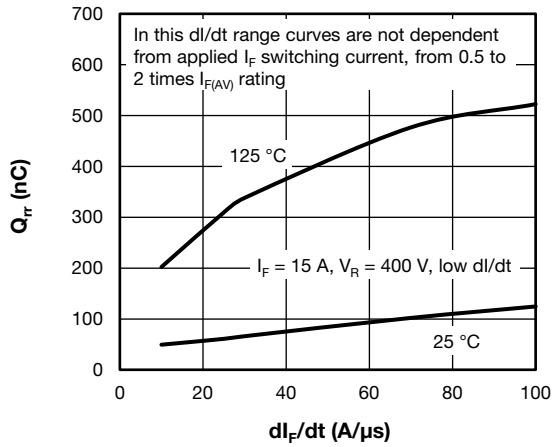


Fig. 11 - Typical Reverse Recovery Charge vs. di_F/dt , Per Leg

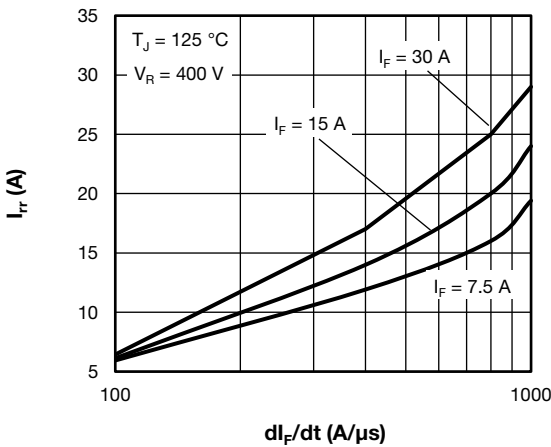


Fig. 9 - Typical Reverse Recovery Current vs. di_F/dt , Per Leg

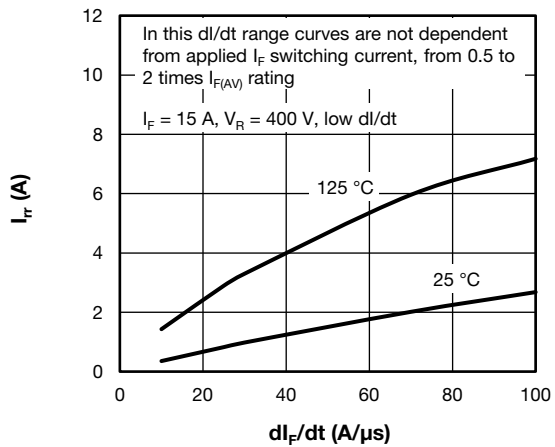


Fig. 12 - Typical Reverse Recovery Current vs. di_F/dt , Per Leg

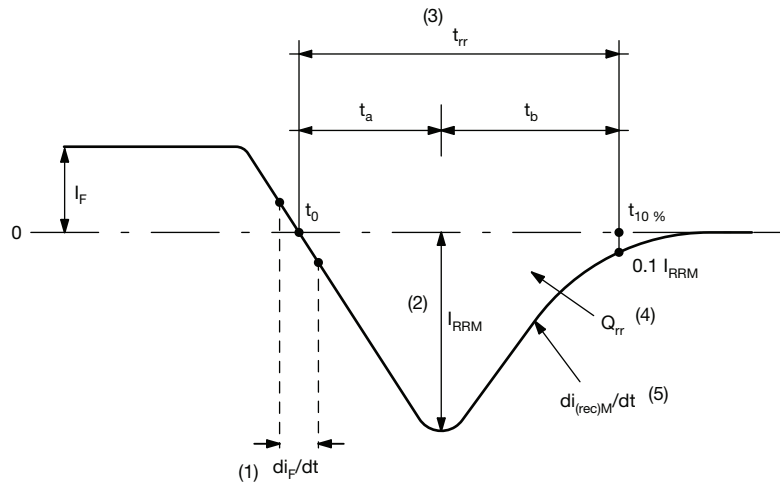


Fig. 13 - Reverse Recovery Waveform and Definitions

Notes

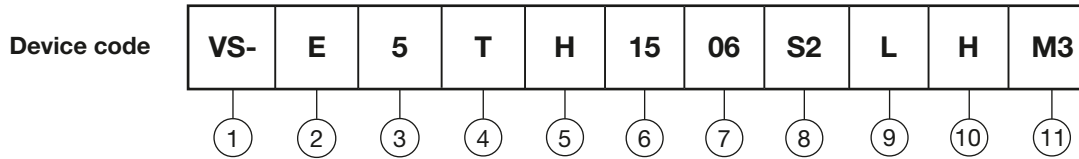
- (1) di_F/dt - rate of change of current through zero crossing
- (2) I_{RRM} - peak reverse recovery current
- (3) t_{rr} - reverse recovery time measured from t_0 , crossing point of negative going I_F , to point $t_{10\%}$, $0.1 I_{RRM}$
- (4) Q_{rr} - area under curve defined by t_0 and $t_{10\%}$

$$Q_{rr} = \int_{t_0}^{t_{10\%}} I(t) dt$$

- (5) $di_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}



ORDERING INFORMATION TABLE



- 1** - Vishay Semiconductors product
- 2** - E = single diode
- 3** - 5 = FRED generation 5
- 4** - Package:
T = D²PAK (TO-263) package
- 5** - H = hyperfast recovery
- 6** - Current rating (15 = 15 A)
- 7** - Voltage rating (06 = 600 V)
- 8** - S2 = true 2 pin D²PAK
- 9** - None = tube (50 pieces)
• L = tape and reel (left oriented, for D²PAK package)
If needed different orientation/packaging, please contact factory
- 10** - H = AEC-Q101 qualified
- 11** - Environmental digit:
M3 = halogen-free, RoHS-compliant, and termination lead (Pb)-free

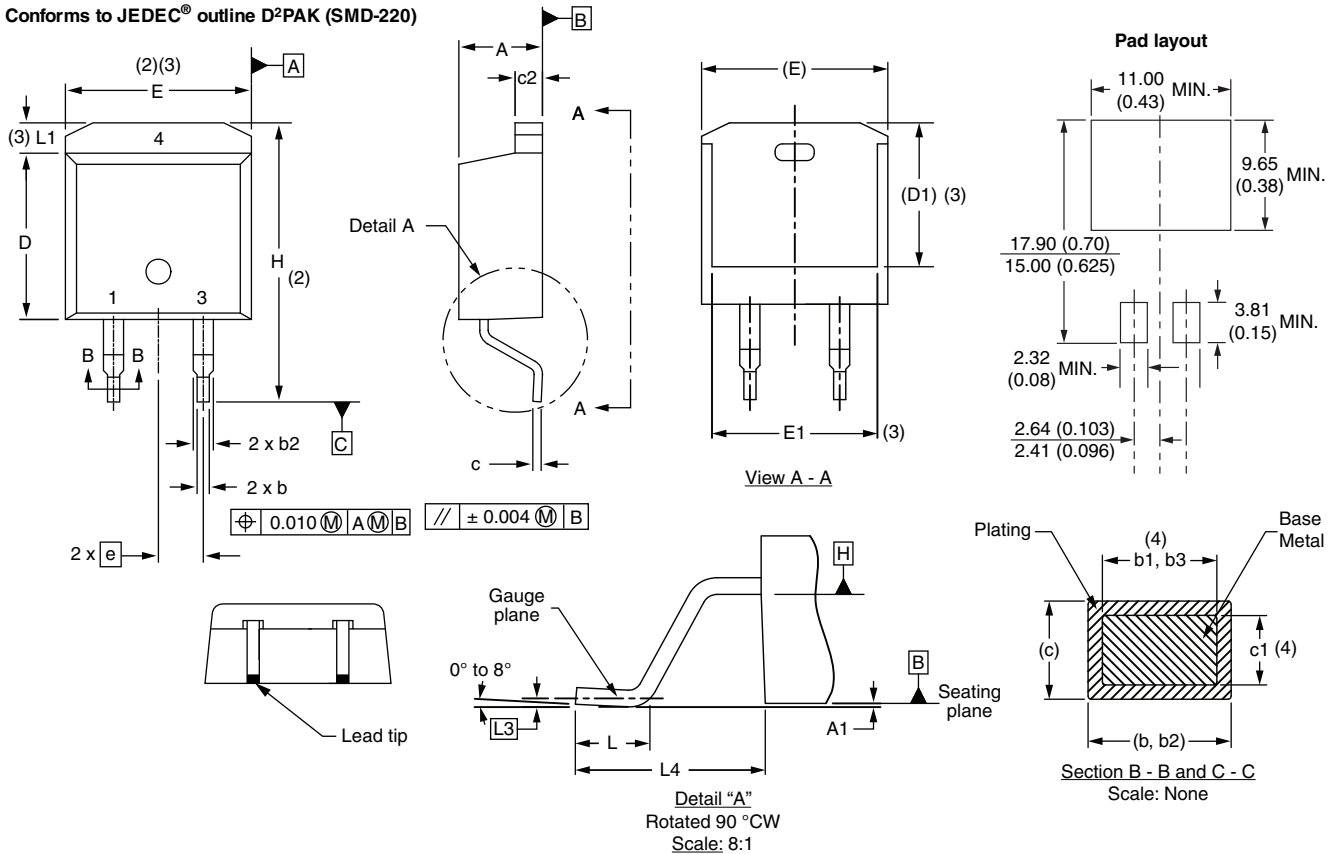
ORDERING INFORMATION (Example)		
PREFERRED P/N	BASE QUANTITY	PACKAGING DESCRIPTION
VS-E5TH1506S2LHM3	800	13" diameter reel

LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?96683
Part marking information	www.vishay.com/doc?96693
Packaging information	www.vishay.com/doc?95032
SPICE Model	www.vishay.com/doc?97158

D²PAK 2L (TO-263AB 2L)

DIMENSIONS in millimeters and inches

Conforms to JEDEC® outline D²PAK (SMD-220)



SYMBOL	MILLIMETERS		INCHES		NOTES	SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.			MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	0.160	0.190		D1	6.86	8.00	0.270	0.315	3
A1	0.00	0.254	0.000	0.010		E	9.65	10.67	0.380	0.420	2, 3
b	0.51	0.99	0.020	0.039		E1	7.90	8.80	0.311	0.346	3
b1	0.51	0.89	0.020	0.035	4	e	2.54 BSC		0.100 BSC		
b2	1.14	1.78	0.045	0.070		H	14.61	15.88	0.575	0.625	
b3	1.14	1.73	0.045	0.068	4	L	1.78	2.79	0.070	0.110	
c	0.38	0.74	0.015	0.029		L1	-	1.65	-	0.066	3
c1	0.38	0.58	0.015	0.023	4	L3	0.25 BSC		0.010 BSC		
c2	1.14	1.65	0.045	0.065		L4	4.78	5.28	0.188	0.208	
D	8.51	9.65	0.335	0.380	2						

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inch
- (7) Outline conforms to JEDEC® outline TO-263AB



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